

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

DFN 3mm X 2mm Exp. Pad

(printed on: 2020-07-11 16:42:11)

TOTAL MASS (g) : 0.014425

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.000778 | 1000000 | 53935.6132812 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.005090 | 975000 | 352869.28125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000125 | 24000 | 8665.74804688 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000002 | 300 | 138.65196228 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000004 | 700 | 277.303924561 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.005221 | 1000000 | 361950.96875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000185 | 1000000 | 12798.0273438 | | |
| | | External Plating Total: | | | | 0.000185 | 1000000 | 12798.0273438 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000103 | 1000000 | 7140.57568359 | | |
| Internal Plating Total: | | | | 0.000103 | 1000000 | 7140.57568359 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000546 | 750000 | 37851.9882812 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000182 | 250000 | 12617.3291016 | | |
| Die Attach Total: | | | | 0.000728 | 1000000 | 50469.3164062 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.000958 | 130000 | 66414.2890625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.006338 | 860000 | 439388.0625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000074 | 10000 | 5130.12304688 | | |
| | | Encapsulation Total: | | | | 0.007370 | 1000000 | 510932.5 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000040 | 1000000 | 2773.03930664 | | |
| | | | | | TOTAL MASS (g) : | 0.014425 | | |